

Wideband RMS-DC Converter Building Block

FEATURES

- 300MHz 3dB Bandwidth
- 1% Accuracy DC-50MHz
- 2% to 100MHz
- Bandwidth Flat Over Input Voltage Range
- 50:1 Crest Factor
- 20:1 Dynamic Range
- 35V Peak Input
- Thermally Based Operation
- **■** Fully Specified Thermal and Electrical Parameters
- Standard IC Packages
- Resistive Inputs

APPLICATIONS

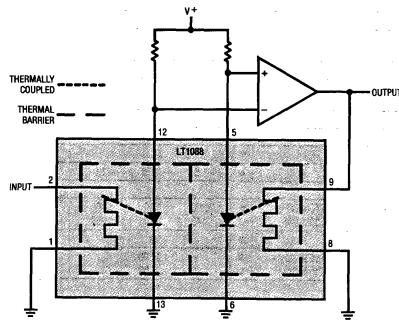
- Wideband RMS Voltmeters
- RF Leveling Loops
- Wideband AGC
- High Crest Factor Measurements
- SCR Power Monitoring

DESCRIPTION

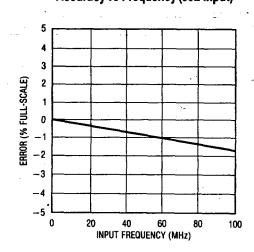
The LT1088 is a thermally based RMS-DC converter building block. It converts the input waveform to heat. Using external circuitry, the thermal signal is expressed as a DC output voltage.

LTC's proprietary thermal packaging process permits accurate thermal signal processing in a standard IC package. The thermal method provides far greater bandwidth than RMS converters based on logarithmic computing techniques. The LT1088's high voltage breakdown allows crest factor measurements of 50:1 and operation over a 20:1 input dynamic range. Resistive inputs of 50\Omega or 250\Omega accommodate drive from a wide variety of sources.

Simplified RMS-DC Converter



Accuracy vs Frequency (50Ω Input)

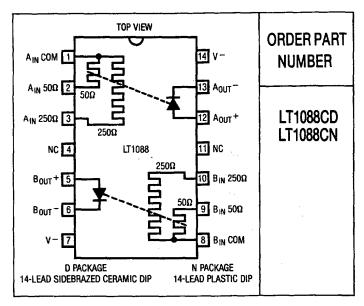


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ABSOLUTE MAXIMUM RATINGS

Voltage on Any Pin	+ 40V to V-
Voltage from Channel A to Channel B	100V
Reverse Diode Voltage	3.5V
Forward Diode Current	
Input Power (25°C)	0.375W
Peak Input Power (30 sec)	0.435W
Derate Power at -3mW/°C above 25°C	
Maximum Die Temperature	150°C
Peak Die Temperature (30 sec)	175°C
Functional Temperature Range – 55	5°C to 125°C
Operating Temperature Range 4	10°C to 85°C
Lead Temperature (Soldering, 10 sec)	

PACKAGE/ORDER INFORMATION



ELECTRICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted (See Note 1)

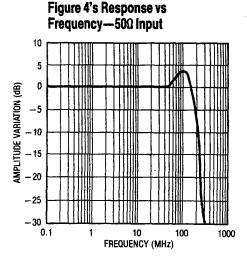
PARAMETER	CONDITIONS			MIN	TYP	MAX	UNITS
Input Heaters							
50Ω Input				40	50	60	Ω
250Ω Input				200	250	300	Ω
50Ω Temperature Coefficient			•		2000		ppm/°C
2500 Temperature Coefficient			•		2000		ppm/°C
50Ω Temperature Coefficient Match	Input A to Input B		•		30	500	ppm
250Ω Temperature Coefficient Match	Input A to Input B		•		30	500	ppm
Resistance Matching	50Ω Inputs 250Ω Inputs				2 2	10 10	% %
250Ω to 50Ω Ratio Match				-15	0	5	%
250Ω to 50Ω Ratio Match Temperature Coefficient			•		50		ppm/°C
Output Diodes							
Forward Voltage	1 = 5mA			0.6	0.7	0.8	٧
Forward Voltage Match	Out A to Out B; I = 5mA		•		5		mV
Voltage Temperature Coefficient	I = 5mA		•	- 1.6	- 1.75	- 1.9	mV/°C
Thermal Characteristics	·						
Thermal Resistance	Either Die to Ambient	LT1088CD LT1088CN	:	200 140	300 210	400 280	°CW
Thermal Matching	Channel A to Channel B		•		30		°C/W
Thermal Cross Talk	Channel A to Channel B	LT1088CD LT1088CN	•		2500 1750		°C/W

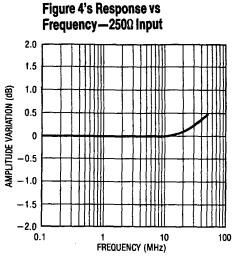
The denotes specifications which apply over full operating temperature range.

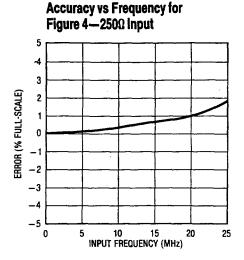
Note 1: All electrical testing conducted at 25°C.



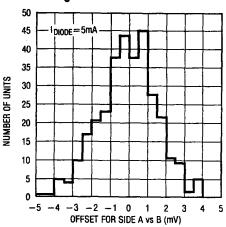
TYPICAL PERFORMANCE CHARACTERISTICS



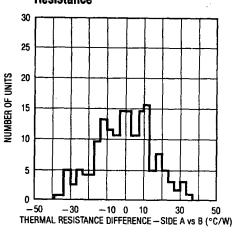




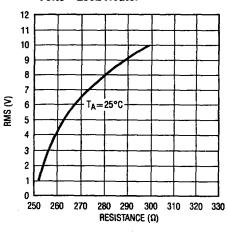
Distribution of Diode Offset Voltage



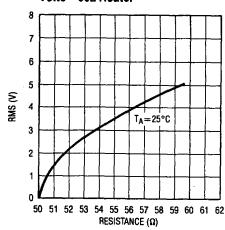
Distribution of Thermal Resistance



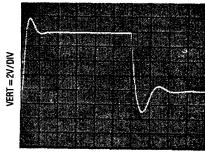
Heater Resistance vs RMS Volts—250Ω Heater



Heater Resistance vs RMS Volts—500 Heater



Figures 4's Settling Time (LT1088CD)



HORIZ = 200ms/DIV





APPLICATIONS INFORMATION

Pin Functions

Ain 50 Ω , Bin 50 Ω , Ain 250 Ω , Bin 250 Ω (Pins 2, 9, 3, 10): Heater input pins. Input and servo amplifier are connected to these pins. Since the LT1088 is symmetrical, either channel A or B may be used as the input. For higher input impedance, the 50 Ω and 250 Ω heaters may be series connected. No heater pin may be below V $^-$ or more than 40V above V $^-$. Maximum heater dissipation must not exceed the absolute maximum ratings.

AIN COM, BIN COM (Pins 1, 8): Common point for the 50Ω and 250Ω input heaters, usually tied to ground.

Aout⁺, Bout⁺ (Pins 12, 5): High side of the temperature sensing diodes. Normally they are driven at 5mA from the positive supply. No diode pin may be below V^- or more than 40V above V^- .

Aout⁻, Bout⁻ (Pins 13, 6): Low side of the temperature sensing diodes. These pins are normally tied to ground. No diode pin may be below V^- or more than 40V above V^- .

 V^- (Pins 7, 14): These pins must be the most negative potential of the circuit, usually tied to ground.

Parasitic Diodes

As with all bipolar ICs the LT1088 contains parasitic diodes which must not be forward biased. The parasitic diodes, marked with asterisks, appear in Figure 1. The

dashed lines indicate that all points of the heaters are parasitically diode connected to V^- .

Thermal Considerations

Because the LT1088's operation depends on thermal symmetry, it is sensitive to external temperature gradients. This is particularly the case for small inputs, which cause the device to run very close to ambient temperature. The device should be mounted in an area which is isothermal and free of drafts. Power generating components should be kept away from the LT1088 and particular caution taken in fan cooled equipment. Under normal conditions no thermal baffle or enclosure is required. Under no circumstances should a heat sink be used.

Heater Protection

Most LT1088 failures will be caused by excessive heater drive. Input power (25°C) is specified at 375mW with 30 second excursions to 435mW permitted. These figures are derated by -3mW/°C above 25°C. Figure 2 plots safe operating limits for input duty cycle vs input voltage. Accidental heater overdrives can damage or destroy the LT1088. In situations where overdrive may occur, some form of heater protection should be employed. Suggested circuits appear in the applications section.

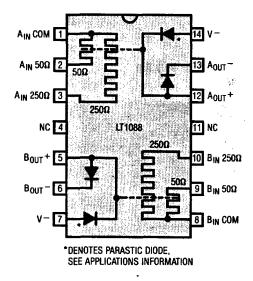


Figure 1

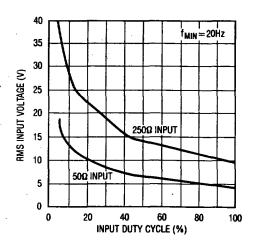


Figure 2. Safe Operating Limits



APPLICATIONS INFORMATION

Filtering

The LT1088's thermal time constant provides effective low pass filtering. Low frequency cut-off is set by servo loop time constants. For the 3300pF value given in the basic RMS-DC application, the circuit begins to follow the input below about 50Hz. Normally, this is not a problem, because the LT1088's primary application will be at high frequency. Lower frequency operation is obtainable by increasing the 3300pF value, although settling time will increase proportionally.

Crest Factor

Crest factor is defined as the ratio of peak input voltage to RMS value. Crest factor performance is set by IC breakdown limits and the usable low input power range. Breakdown limits are a function of processing. The usable low input power range is a basic signal-to-noise conflict. Low input power produces small amounts of signal. This makes accurate, stable discrimination between desired inputs and ambient thermal phenomena uncertain and noisy. These constraints set crest factor at 50:1 for the 50Ω input and 40:1 for the 250Ω input.

Layout

At frequencies above 10MHz, input connections require care. Parasitic inductance builds quickly in wire runs, so

the LT1088's input heater lead should be *directly* connected to the source to be measured. It is also wise to shield the input line from the rest of the circuit. The heater common should be returned directly to a ground plane. An additional precaution is to mount the $0.01\mu F$ bypass capacitors right at the LT1088 package. These units minimize the effects of RF pick-up by the temperature sensing diodes.

· If the part and

Accuracy

Amplitude measurement at high frequency to significant accuracy is difficult because of parasitic effects. At frequencies much above 5MHz, small parasitic capacitive and inductive terms become important. The accuracy figures quoted for the applications circuits were taken against certified standards utilizing direct and transfer techniques. Thermal transfer standards (Fluke Model 540B with A-55 converters) certified to 50MHz were used as references. The data above 50MHz was also taken with these references, although the individual units used had not been certified at these frequencies. The accuracy of units of this type which have been certified is normally inside the tolerances listed, so there is good probability the data is valid.

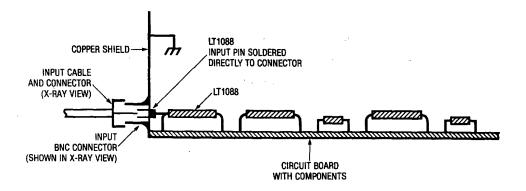


Figure 3. Typical Evaluation Layout



APPLICATIONS INFORMATION

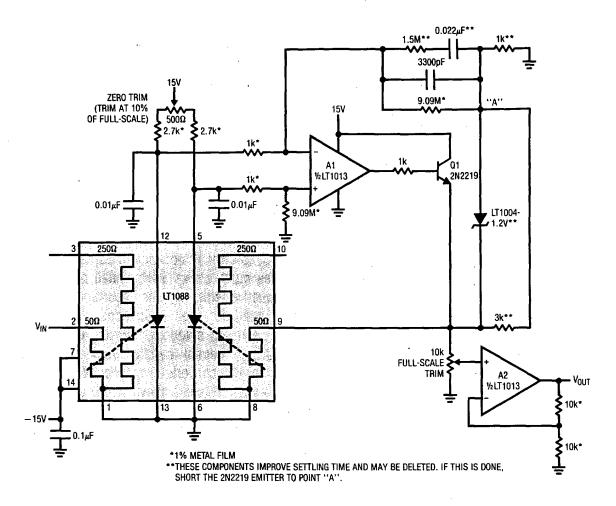
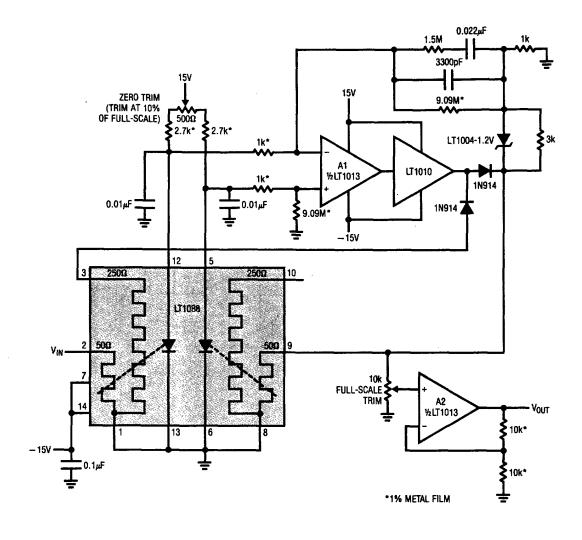


Figure 4. Basic RMS-DC Converter

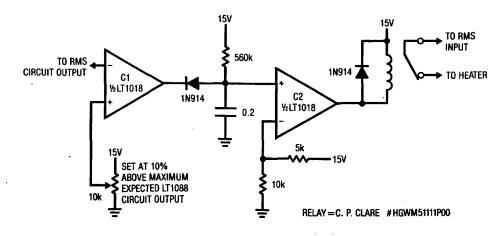
Figure 4's Typical Specifications

50Ω Input DC to 50MHz	
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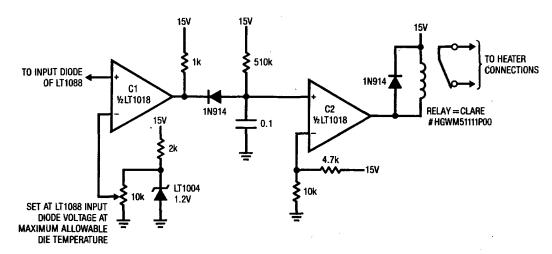
Fast Settling RMS-DC Converter



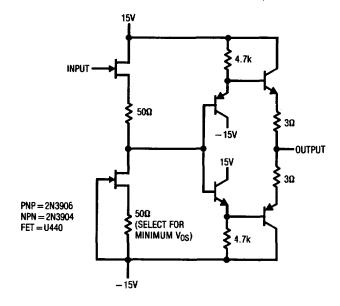
Servo-Sensed Heater Protection Circuit (≈50ms Response)



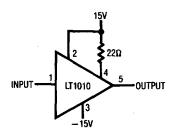
Diode Sensed Heater Protection Circuit (≈15ms Response)



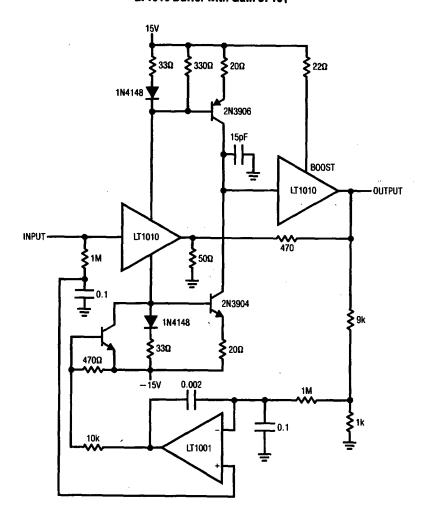
Discrete Input Buffer for the LT1088



LT1010 Buffer†



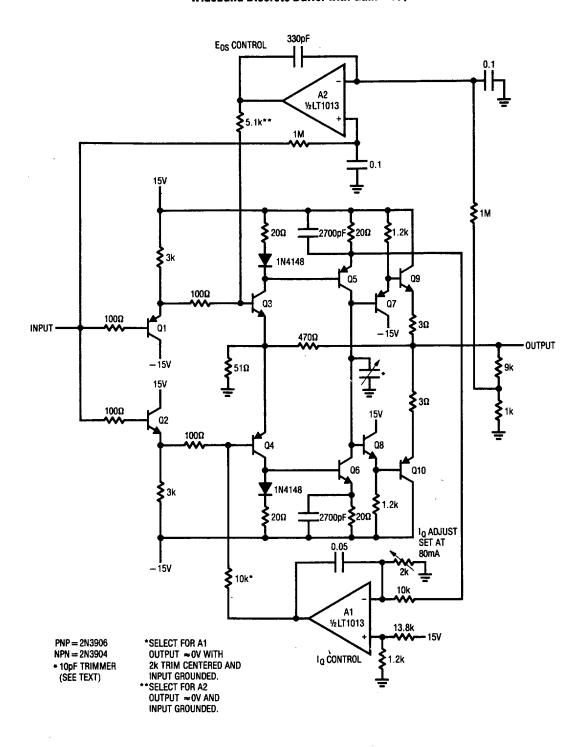
LT1010 Buffer with Gain of 10†



† See Summary of Buffer Characteristics table for buffer speed.



Wideband Discrete Buffer with Gain = 10†



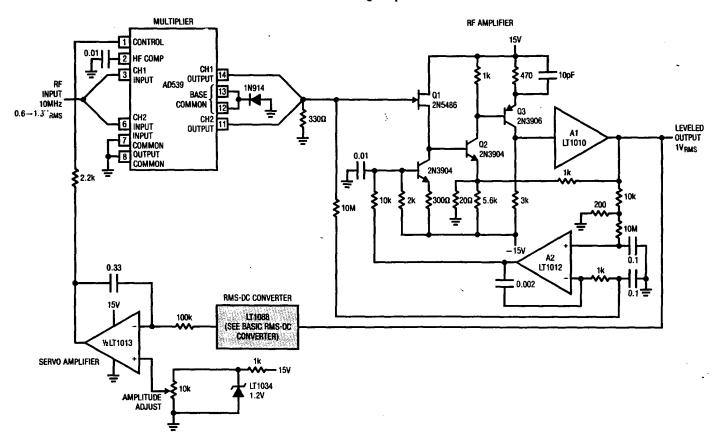
† See Summary of Buffer Characteristics table for buffer speed.



Summary of Buffer Characteristics

Type of Buffer		1% Error Bandwidth		
	Slew Rate	250Ω Load (±10V _{OUT})	50Ω Load (±5V _{OUT})	
Discrete—A = 10	3000V/μs	25MHz	32MHz	
LT1010 Based-A = 10	100V/µs	0.75MHz	2MHz	
Discrete—A=1	2000V/µs	15MHz	25MHz	
LT1010 Based—A = 1	100V/μS	0.75MHz	2MHz	

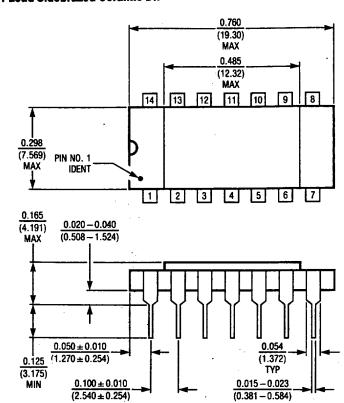
RF Leveling Loop





PACKAGE DESCRIPTION Dimensions in inches (millimeters) unless otherwise noted.

D Package 14-Lead Sidebrazed Ceramic DIP



0.77.0 (19.558)MAX

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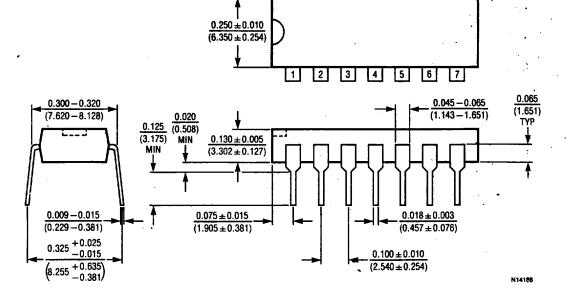
9 8

0.008 - 0.015(0.203 - 0.381)0.300 (7.620) REF

N Package 14-Lead Plastic DIP

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D14188